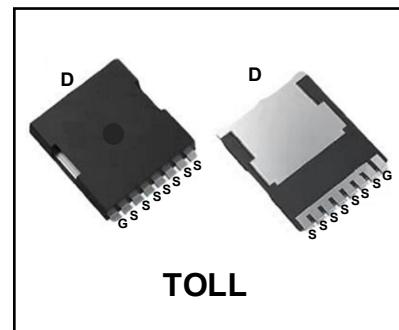


# WMLL020N10HG4

## 100V N-Channel Enhancement Mode Power MOSFET

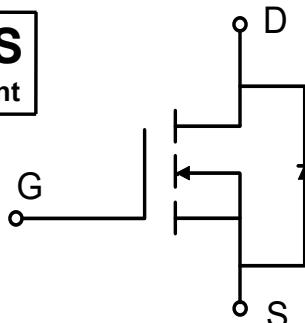
### Description

WMLL020N10HG4 uses Wayon's 4<sup>th</sup> generation power trench MOSFET technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance. This device is well suited for high efficiency fast switching applications.



### Features

- $V_{DS} = 100V$ ,  $I_D = 304A$
- $R_{DS(on)} < 2.0m\Omega$  @  $V_{GS} = 10V$
- High Speed Power Switching
- Low Gate Charge
- Low  $R_{DS(ON)}$
- 100% EAS Guaranteed



### Applications

- DC/DC Converter
- Power Management Switching
- Motor Driver

### Absolute Maximum Ratings ( $T_A = 25^\circ C$ , unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain-Source Voltage		$V_{DS}$	100	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$T_C=25^\circ C$	$I_D$	304	A
	$T_C=100^\circ C$		192	
Pulsed Drain Current <sup>1</sup>		$I_{DM}$	1216	A
Single Pulse Avalanche Energy <sup>2</sup>		$E_{AS}$	2312	mJ
Total Power Dissipation	$T_C=25^\circ C$	$P_D$	468.7	W
Operating Junction and Storage Temperature Range		$T_J$ , $T_{STG}$	-55 to 175	°C

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>3</sup>	$R_{\theta JA}$	39	°C/W
Thermal Resistance from Junction-to-Case	$R_{\theta JC}$	0.32	°C/W

**Electrical Characteristics ( $T_J = 25^\circ\text{C}$ , unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	100	-	-	V
Gate-body Leakage current	$I_{GSS}$	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$	-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current $T_J=25^\circ\text{C}$	$I_{DSS}$	$V_{DS} = 100\text{V}, V_{GS} = 0\text{V}$	-	-	1	$\mu\text{A}$
$T_J=100^\circ\text{C}$			-	-	100	
Gate-Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2	3	4	V
Drain-Source on-Resistance <sup>4</sup>	$R_{DS(\text{on})}$	$V_{GS} = 10\text{V}, I_D = 20\text{A}$	-	1.5	2.0	$\text{m}\Omega$
Forward Transconductance <sup>4</sup>	$g_{fs}$	$V_{DS} = 10\text{V}, I_D = 20\text{A}$	-	67	-	S
<b>Dynamic Characteristics<sup>5</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 50\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$	-	7885	-	pF
Output Capacitance	$C_{oss}$		-	2080	-	
Reverse Transfer Capacitance	$C_{rss}$		-	35	-	
Gate Resistance	$R_g$	f=1MHz	-	3.5	-	$\Omega$
<b>Switching Characteristics<sup>5</sup></b>						
Total Gate Charge	$Q_g$	$V_{GS} = 10\text{V}, V_{DS} = 50\text{V}, I_D = 20\text{A}$	-	125	-	nC
Gate-Source Charge	$Q_{gs}$		-	33	-	
Gate-Drain Charge	$Q_{gd}$		-	32	-	
Turn-on Delay Time	$t_{d(on)}$	$V_{GS} = 10\text{V}, V_{DD} = 50\text{V}, R_G = 3\Omega, I_D = 20\text{A}$	-	27.6	-	ns
Rise Time	$t_r$		-	55	-	
Turn-off Delay Time	$t_{d(off)}$		-	90	-	
Fall Time	$t_f$		-	65	-	
Body Diode Reverse Recovery Time	$t_{rr}$	$I_F = 20\text{A}, dI/dt = 100\text{A}/\mu\text{s}$	-	106	-	ns
Body Diode Reverse Recovery Charge	$Q_{rr}$		-	255	-	nC
<b>Drain-Source Body Diode Characteristics</b>						
Diode Forward Voltage <sup>4</sup>	$V_{SD}$	$I_S = 20\text{A}, V_{GS} = 0\text{V}$	-	-	1.2	V
Continuous Source Current	$T_c = 25^\circ\text{C}$	$I_S$	-	-	304	A

Notes:

- Repetitive rating, pulse width limited by junction temperature  $T_{J(\text{MAX})} = 175^\circ\text{C}$ .
- The EAS data shows Max. rating . The test condition is  $V_{DD}=90\text{V}, V_{GS}=10\text{V}, L=1\text{mH}$ .
- The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
- The data tested by pulsed , pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$ .
- This value is guaranteed by design hence it is not included in the production test.

## Typical Characteristics

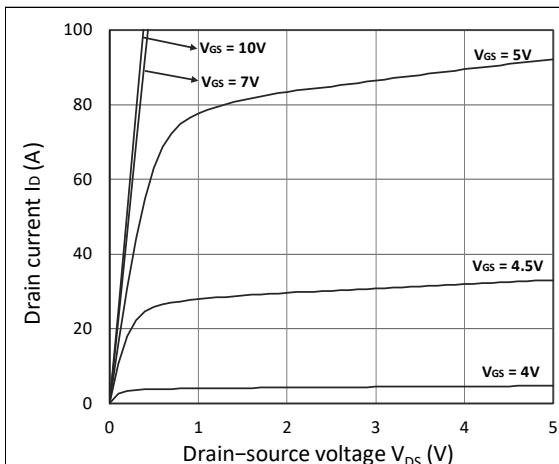


Figure 1. Output Characteristics

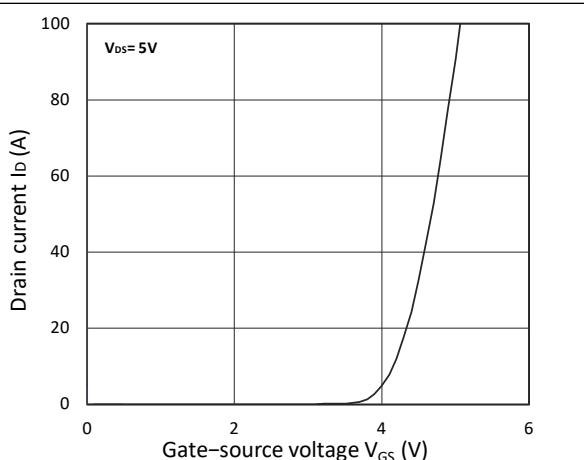


Figure 2. Transfer Characteristics

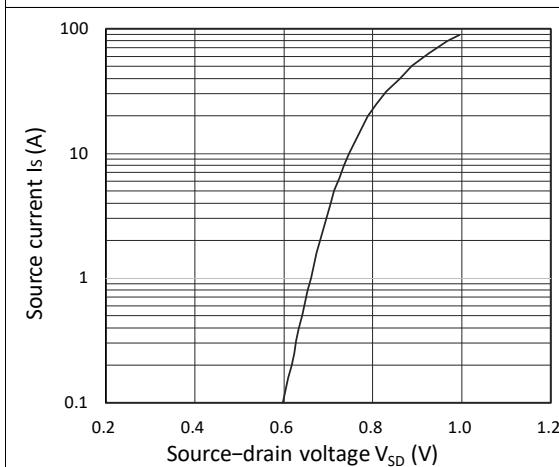
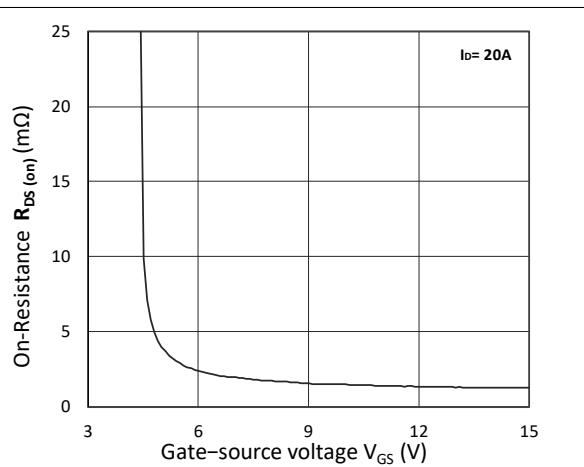
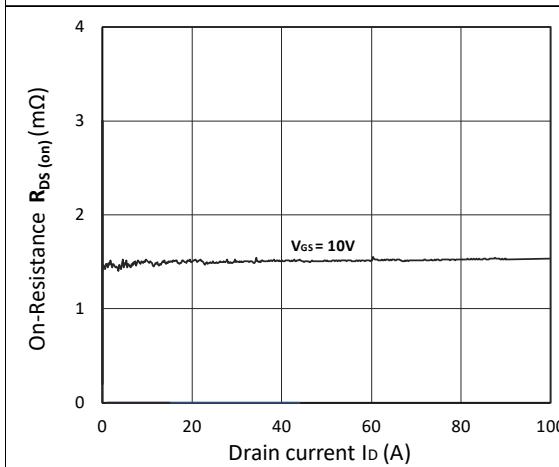
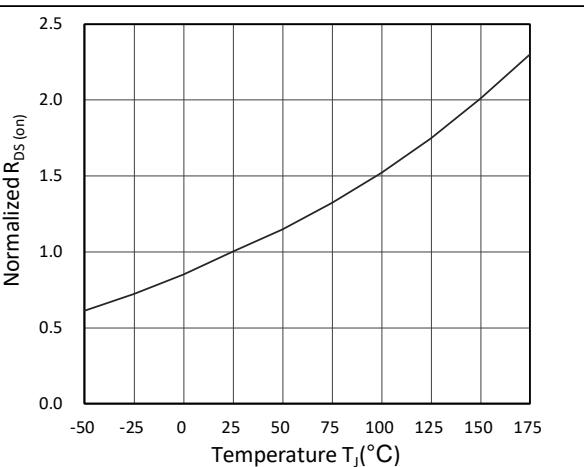
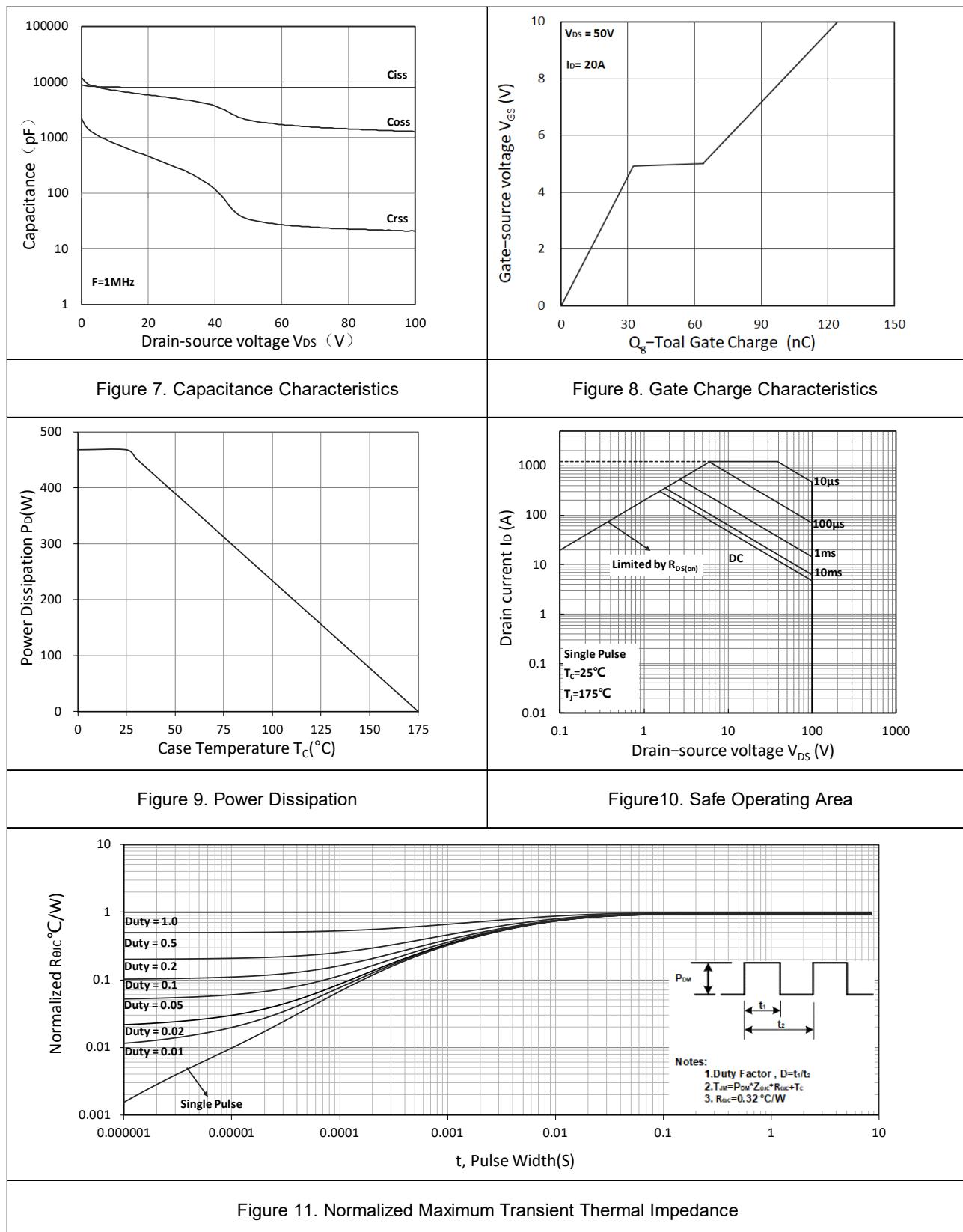
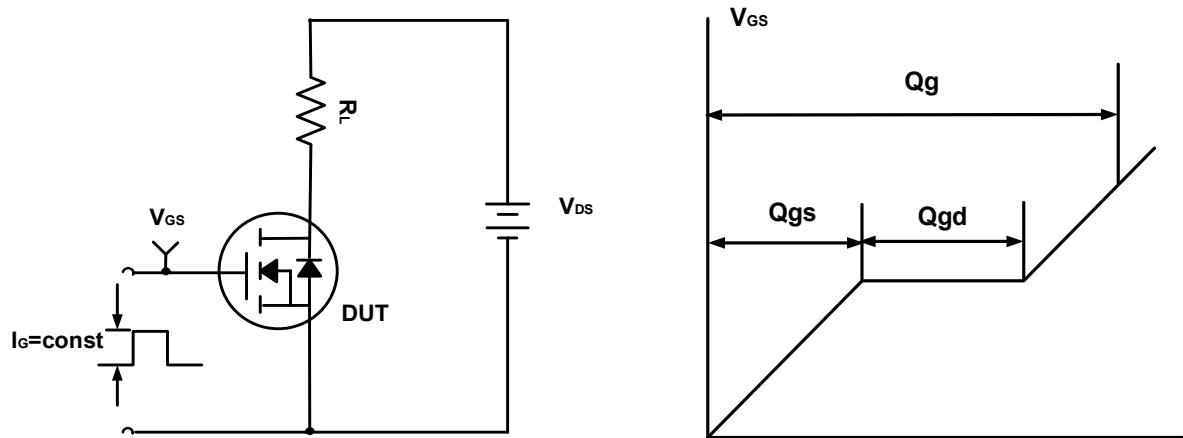
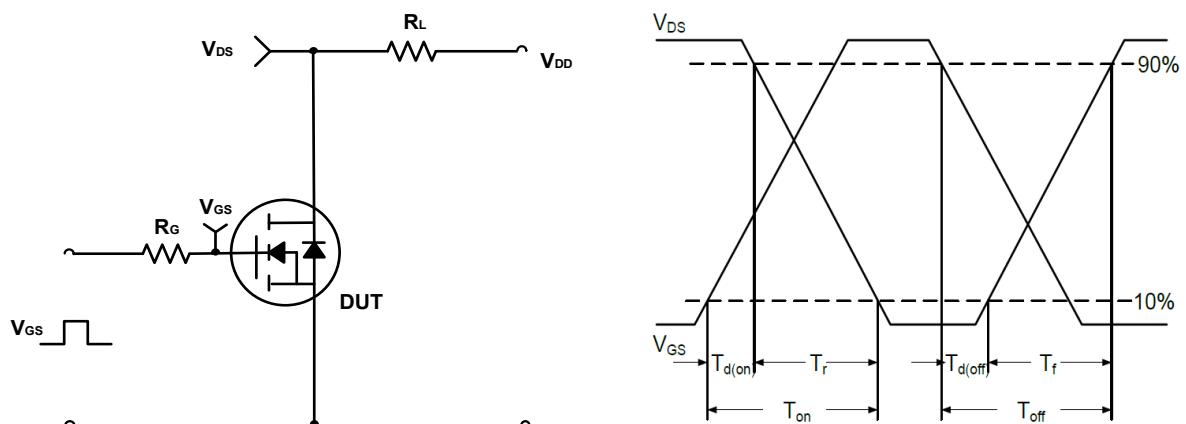
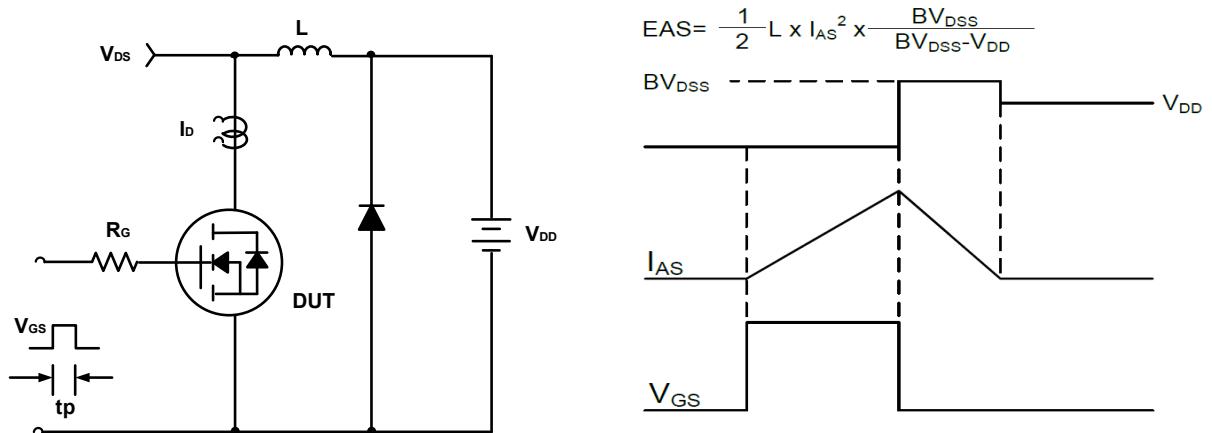


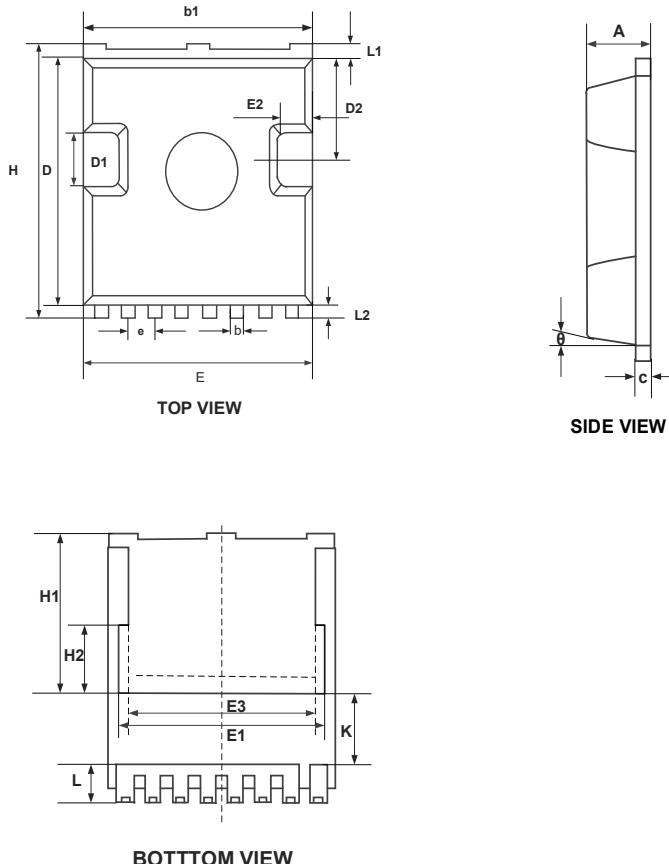
Figure 3. Forward Characteristics of Reverse

Figure 4.  $R_{DS(on)}$  vs.  $V_{GS}$ Figure 5.  $R_{DS(on)}$  vs.  $I_D$ Figure 6. Normalized  $R_{DS(on)}$  vs. Temperature



**Test Circuit****Figure A. Gate Charge Test Circuit & Waveforms****Figure B. Switching Test Circuit & Waveforms****Figure C. Unclamped Inductive Switching Circuit & Waveforms**

## Mechanical Dimensions for TOLL



## COMMON DIMENSIONS

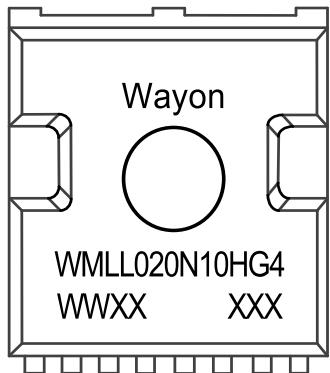
SYMBOL	MM	
	MIN	MAX
A	2.20	2.40
b	0.60	0.90
b1	9.70	9.90
c	0.40	0.60
D	10.20	10.60
D1	3.10	3.50
D2	4.45	4.75
E	9.70	10.10
E1	9.20BSC	
E2	0.50	0.70
E3	7.80BSC	
e	1.20 BSC	
H	11.45	11.90
H1	6.75 BSC	
H2	2.80 BSC	
K	3.10 REF	
L	1.70	2.10
L1	0.60	0.80
L2	0.50	0.70
$\theta$	10° REF	

## WMLL020N10HG4

### Ordering Information

Part	Package	Marking	Packing method
WMLL020N10HG4	TOLL	WMLL020N10HG4	Tape and Reel

### Marking Information



WMLL020N10HG4 = Device code

WWXX XXX= Date code